Application

- Communication for wireless and broad-band
- receiver
- Communication Test Equipment
- subsystem of Radar and satellite
- Power Amplifier linearization

Features

- Resolution：14bit
- sample rate：250MSPS
- SNR > 65dB；
- SFDR > 70dB；
- Power Consumption:< 0.45W
- PIN and ADS4149 series Compatible

Description

The BM41AD49QF of 14-bit A/D Converter（ Analog-to-Digital Converter) with sampling rates up to 250MSPS is monolithic integrated circuits manufactured using CMOS Technology， this Converter has characteristics of high speed and high precision. A new design approach is taken advantage in this A/D Converter to achieve high dynamic performance as well as ultra-low-power at 1.8V supply. It is can be used for multi-carrier broadband communication application.

The elementary diagram of A/D Converter. This circuit include pipelining processing, out driver circuit, internal generation reference circuit， Clock duty cycle stabilizer， control logic and digital Correction circuit.

This circuits are available in a compact QFN-48 package and can alternative similar products of ADS4149 made by Texas Instrument (TI).
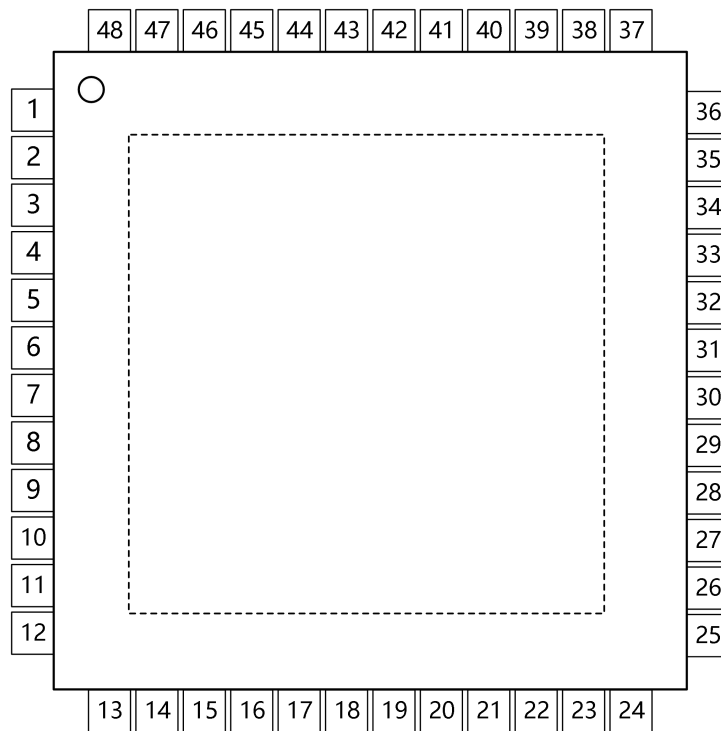
Pin Configurations

Figure 1.1. Pin Configuration

Catalog

Revision Log

Version	Revision date	Change content	Reason for Change	Modified by	Reviewed By	Note
V1.0	2025.5.13	Add the configuration data of the product registers.	Error update	WW	LYL	

Pin Description

Pin Number	Symbol	Pin Description	Pin Number	Symbol	Pin Description
1	GND$_D$	Digital ground	25	GND$_A$	Simulation ground
2	VDDD	Digital power	26	VDDA	Simulation power
3	QOR	Overflow bit	27	SEN	Serial interface enable
4	QCLK-	Clock output (-)	28	SDATA	Serial interface data input
5	QCLK+	Clock output (+)	29	SCLK	Serial interface clock input
6	DFS	Output data format	30	RESET	Reset
7	OE	Output enables	31	DNC	No connection
8	VDDA	Analogue power	32	DNC	No connection
9	GND$_A$	Analogue ground	33	DD0-/DD1-	D0、D1 Negative output of D0、D1
10	INCLK+	Differential clock input (+)	34	DD0+/DD1+	D0、D1 Positive output of D0、D1
11	INCLK-	Differential clock input (-)	35	VDDD	Digital Power
12	GND$_A$	Analogue ground	36	GND$_D$	Digital ground
13	VCM	Common-mode input	37	DD2-/DD3-	D2、D3 Negative output of D2、D3
14	GND$_A$	Analogue ground	38	DD2+/DD3+	D2、D3 Positive output of D2、D3
15	IN+	Differential analogue input (+)	39	DD4-/DD5-	D4、D5 Negative output of D4、D5
16	IN-	Differential analogue input (-)	40	DD5+/DD5+	D4、D5 Positive output of D4、D5
17	GND$_A$	Analogue ground	41	DD6-/DD7-	D6、D7 Negative output of D6、D7
18	VDDA	Analogue power	42	DD6+/DD7+	D6、D7 Positive output of D6、D7
19	GND$_A$	Analogue ground	43	DD8-/DD9-	D8、D9 Negative output of D8、D9
20	VDDA	Analogue power	44	DD8+/DD9+	D8、D9 Positive output of D8、D39
21	DNC	No connection	45	DD10-/DD11-	D10、D11 Negative output of

					D10、D11
22	VDDA	Analogue power	46	DD10+/DD11+	D10、D11 Positive output of D10、D11
23	DNC	Backup	47	DD12-/DD13-	D12、D13 Negative output of D12、D13
24	VDDA	Analogue power	48	DD12+/DD13+	D12、D13 Positive output of D12、D13

Figure 1.2 Pin Description
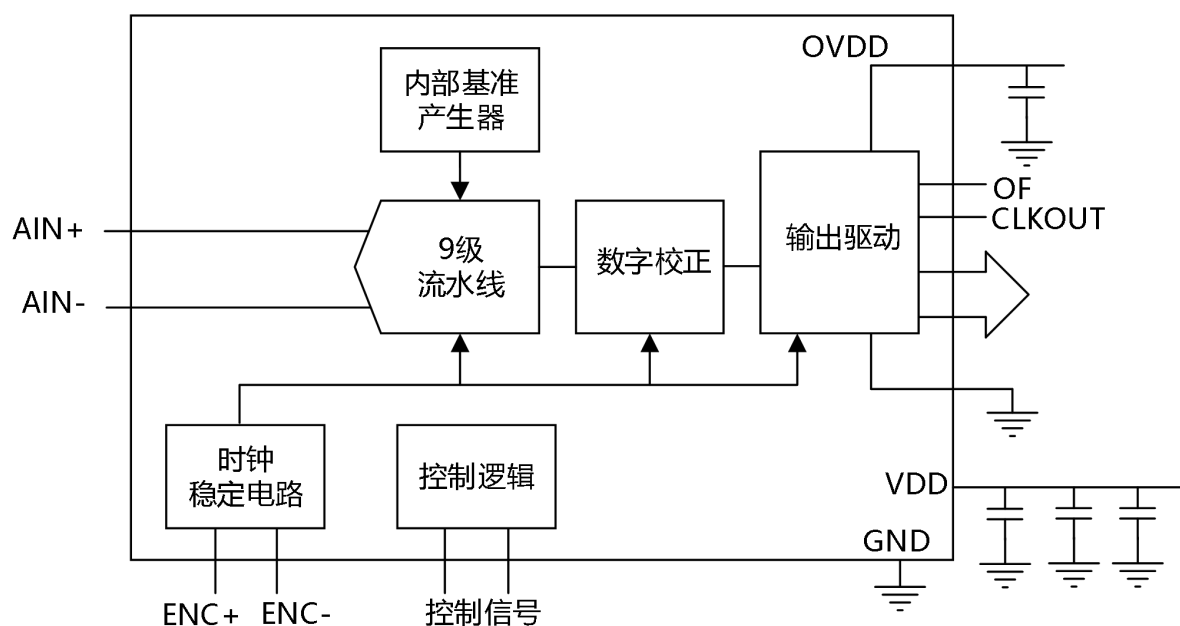
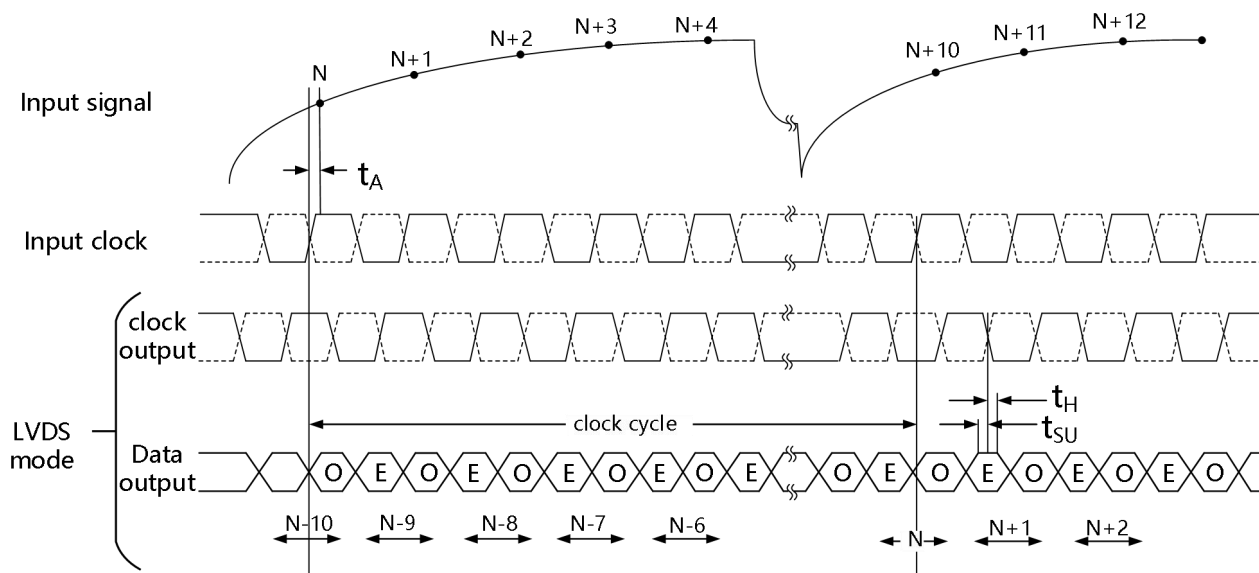# Block Diagram and Timing Characteristics

Figure 1.3 Block Diagram

Figure 1.4 Timing characteristics

Performance Parameter

Parameter	Test Condition	14-bit 250MHz ADC			Unit
		Min	Typ	Max	
Resolution	-		14		Bit
SNR	f_{LK}=250MHz, f_{IN}=30MHz	69	71	-	dBFS
	f_{LK}=250MHz, f_{IN}=70MHz	68	70	-	
	f_{LK}=250MHz, f_{IN}=170MHz	67	69	-	
SINAD	f_{LK}=250MHz, f_{IN}=30MHz	68	70	-	dBFS
	f_{LK}=250MHz, f_{IN}=70MHz	67	69	-	
	f_{LK}=250MHz, f_{IN}=170MHz	66	68	-	
SFDR	f_{LK}=250MHz, f_{IN}=30MHz	78	82	-	dBFS
	f_{LK}=250MHz, f_{IN}=70MHz	77	80	-	
	f_{LK}=250MHz, f_{IN}=170MHz	76	78	-	
ENOB	f_{LK}=250MHz, f_{IN}=30MHz	10.5	-	-	Bit
DNL	f_{LK}=250MHz, f_{IN}=10MHz	-0.99	±0.8	-	LSB
INL	f_{LK}=250MHz, f_{IN}=10MHz	-	±3.5	±5	LSB
digital characters					
Differential Input Voltage Range	—	-	2	-	Vpp
Input Resistance	—	-	1	-	MΩ
input capacitance	—	-	4	-	pF
Analogue input bandwidth	—	-	480	-	MHz
Common-Mode Output Voltage	—	-	0.95	-	V
DC characters					
offset error	—	-15	3	15	mV
gain error	—	-2	-	2	%FS
power dissipation					
Analog Current	LVDS mode (350mV)	-	138	150	mA
digit current	LVDS mode (350mV)	-	65	80	mA
Analog power consumption	LVDS mode (350mV)	-	248.4	270	mW

Digital power consumption	LVDS mode (350mV)	-	117	144	mW
Sleep power consumption	LVDS mode (350mV)	-	3.5	25	mW
digital characters					
Input Logic Voltage High	—	1.5	-	—	V
Input Logic Voltage Low	—	—	-	0.3	V
Input Logic Voltage High	—	-15	-	15	uA
Low input current	—	-2	-	2	uA
LVDS differential output voltage	LVDS mode (350mV)	200	350	500	mV
LVDS common-mode output voltage	LVDS mode (350mV)	0.8	1.05	1.3	V
time parameter					
Aperture delay	-	0.6	0.8	1.2	ns
Data setting time	LVDS mode (350mV)	0.35	0.6	-	ns
Data holding time	LVDS mode (350mV)	0.75	1.1	-	ns

Figure 1.5 performance parameter list

Curve diagram of Main characteristics(test chart of electrical characteristics)

1、 **Test condition for the test result of DNL、INL:**

Sampling rates（SR）: f_{CLK}=250MHz;

Frequency of input signal f_{IN}=10MHz;

Test result: DNL: +0.8/-0.75 LSB

INL: +4.1/-3.8 LSB
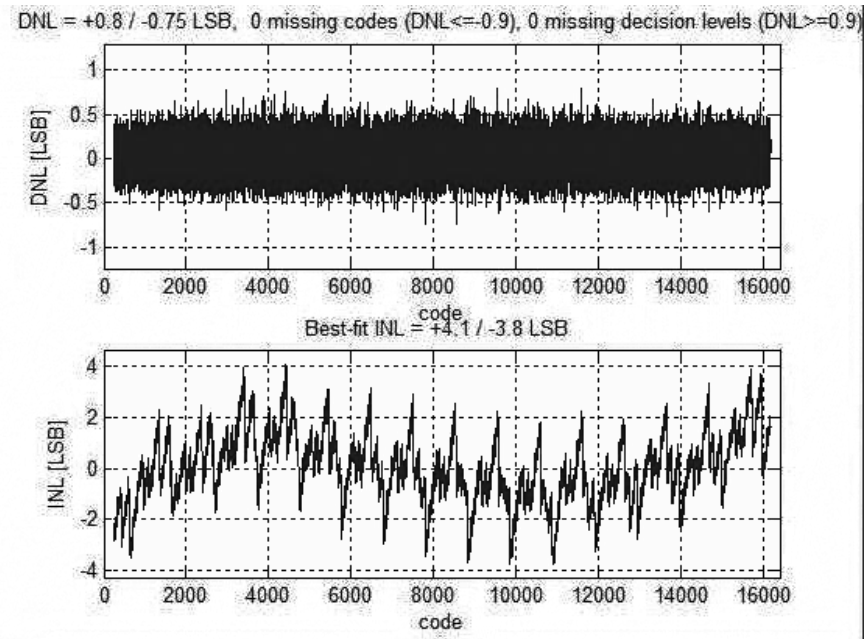
Figure 1.6 Test result of DNL and INL

2．Test condition for the test result of dynamic parameter:
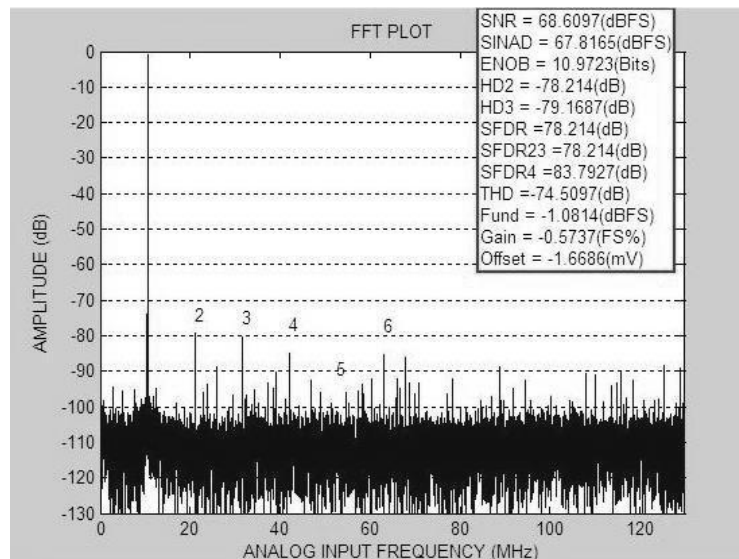
Sampling rates（SR）：f_{CLK}=250MHz;

Frequency of input signal：f_{IN}=10MHz;

Test result：SFDR=78dB;

HD2，3nd=78dB;

HD4nd=83dB;

SNR=68.6dB;

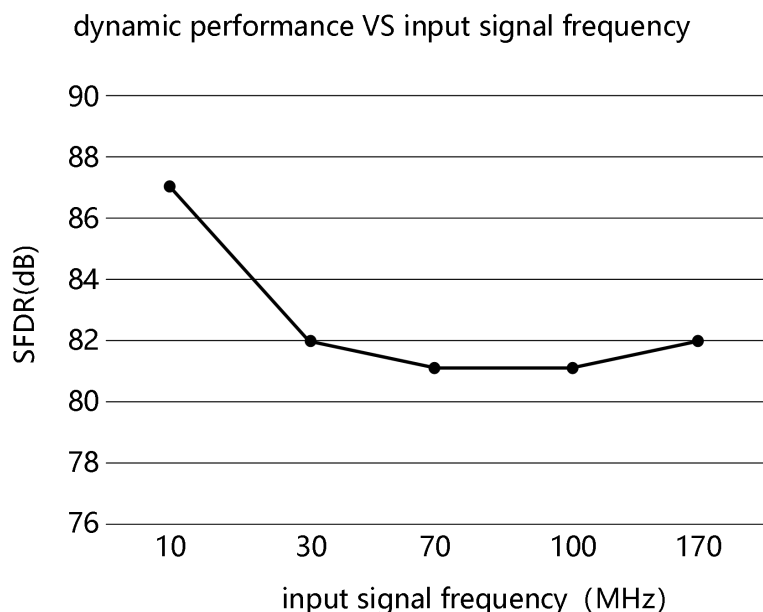dynamic performance VS input signal frequency

Figure 1.8 dynamic performance index VS frequency

Typical Application Circuit

1. Generation

The 14-bit A/D Converter (Analog-to-Digital Converter) is monolithic integrated circuits manufactured using CMOS Technology. It has characteristics of high sampling rate, small linear error, offset gain factor calibration, interface control and so on. Through SPI interface, the converter can configure operating condition of interior circuit, input offset and full-scale input range. The Analogue input which is differential input is AC-coupled or DC-coupled input. DC Bias is set in the interior of clock input circuit which input must be DC-coupled.

this Converter has characteristics of high speed and high precision. A new design approach is taken advantage in this A/D Converter to achieve high dynamic performance as well as ultra-low-power at 1.8V supply. It is can be used for multi-carrier broadband communication application.

2. Analogue input

Analogue input use differential structure based on open-off capacity, this structure has capacity of sampling and holding function. As shown in Figure 1.9 , the differential structure appear to better AC character. The common-mode voltage of Differential input of INP and INM is 0.95V, this voltage is provided by pin $V_{CM.}$ The maximum swing of differential input is 2VPP.
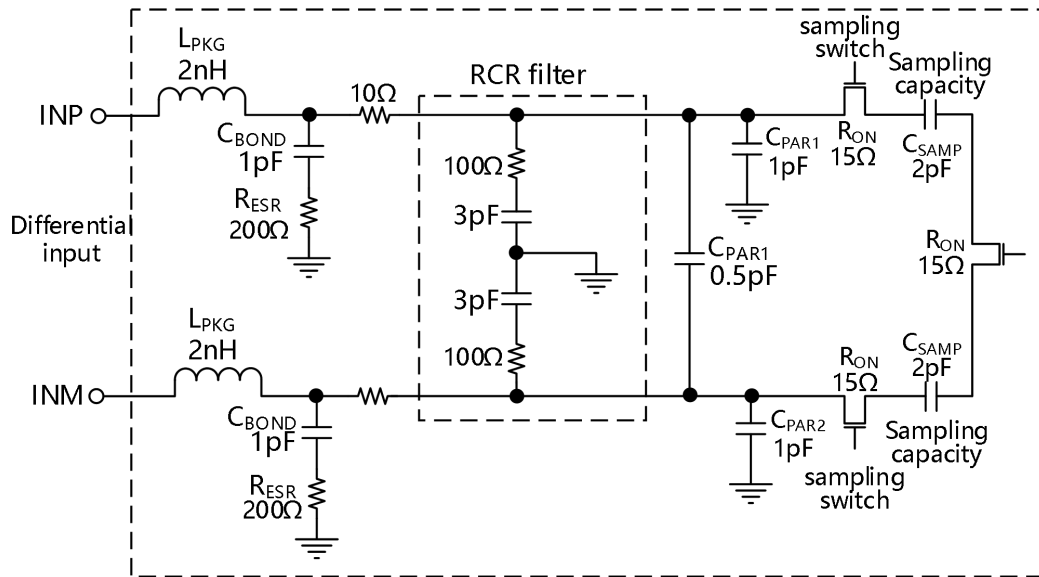
Figure 1.9 equivalent circuit of analog input

3. Driver circuit

Fig. 2.0（a）and Fig. 2.0（b）show two Configurations for driver circuit: one is optimized from low bandwidth and the other is optimized from high bandwidth (The purpose of using high bandwidth is to support high input frequency).
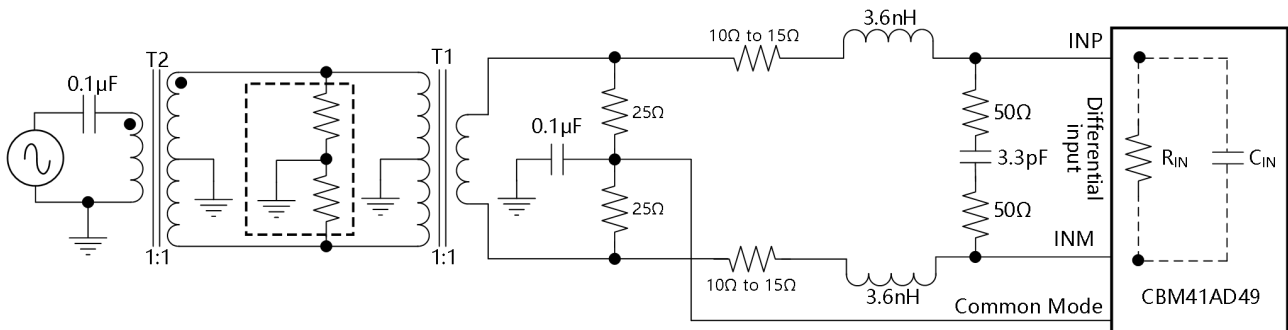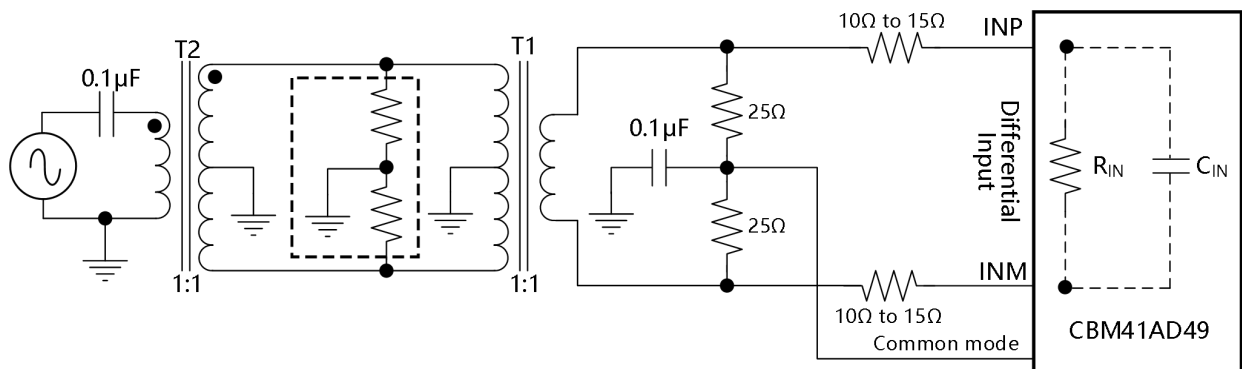

Figure 2.0 （a）low-frequency analog input drive circuit

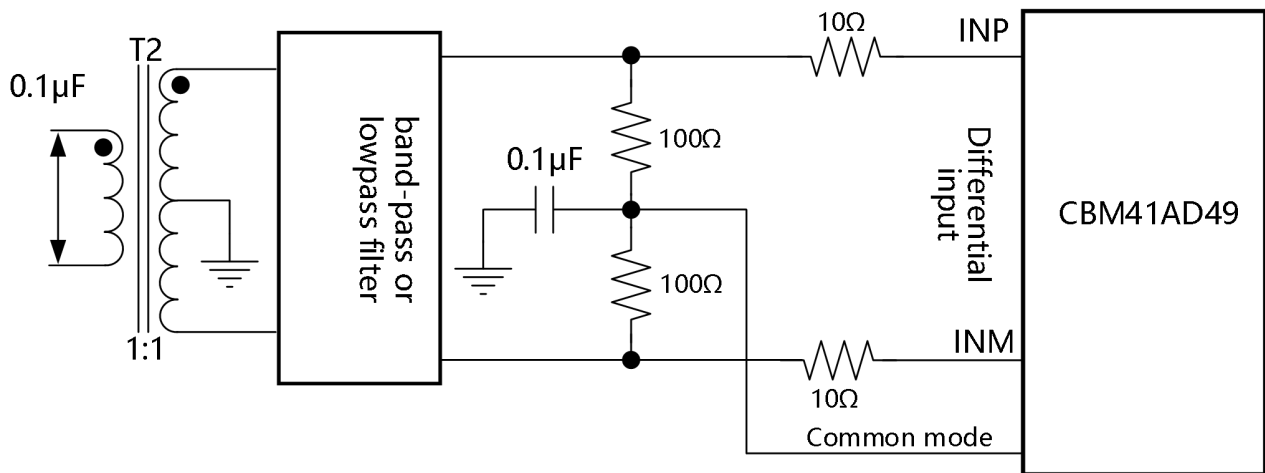Figure 2.0（b）high-frequency analog input drive circuit

Figure 2.1 drive circuit of transformer of one forth

Figure 12 illustrates in each case aid of band pass or lowpass filters is need to obtain dynamic performance the circuit need, The result of using this filter would produce lower source impedance and the advantage of it is not only to absorption peak but also not to cause performance degradation.

4. clock input

Clock input of product can be driven by either difference (Sine wave generator, LVPECL or LVDS) or single end (LVCMOS). Application of transformer coupling in driving circuit could be adopted as sinusoidal clock signal inputting and in the same application of alternating current coupling as LVPECL or LVDS inputting. Figure 2.2 illustrates an equivalent circuit for clock input.
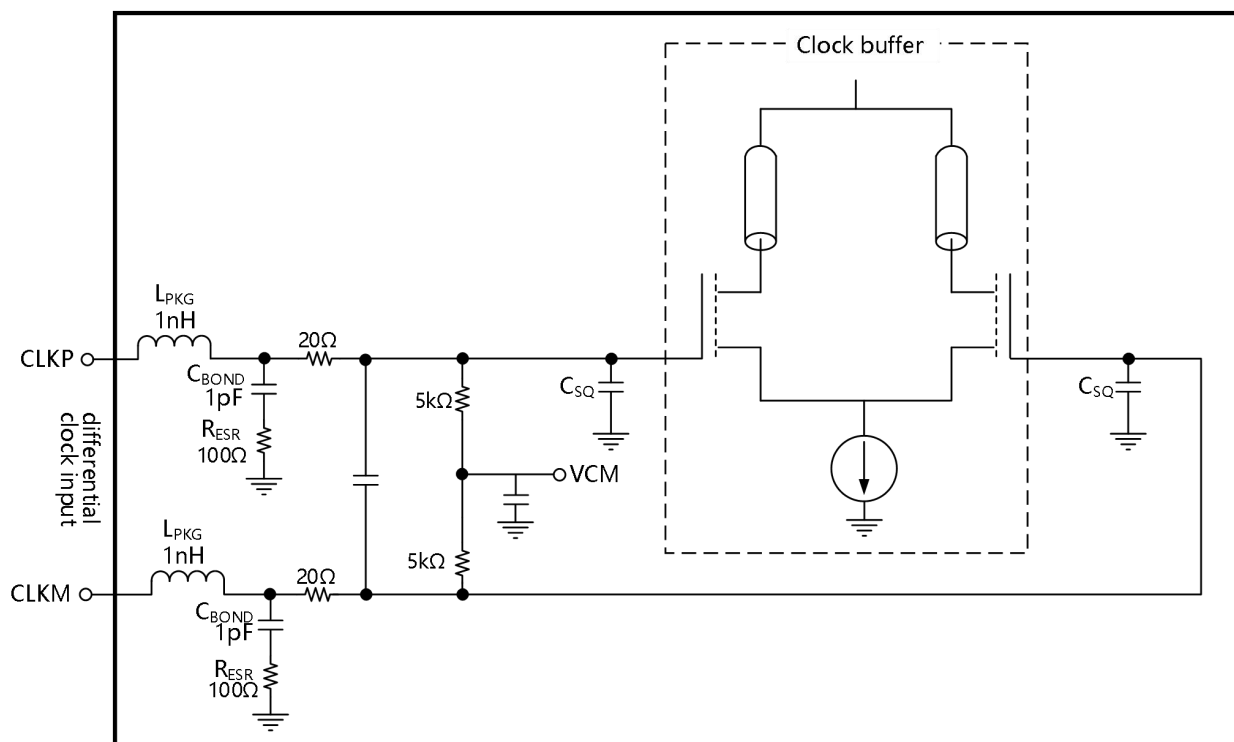
Figure 2.2 equivalent circuit of input clock

Figure 2.3 illustrates single-ended clock driving circuit，Figure 2.3 illustrates differential clock driving circuit.
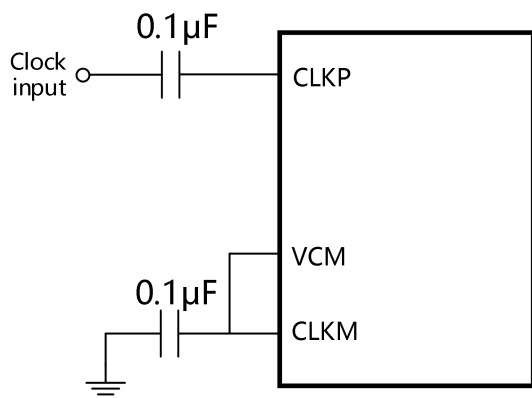
Figure 2.3 single-ended clock driving circuit
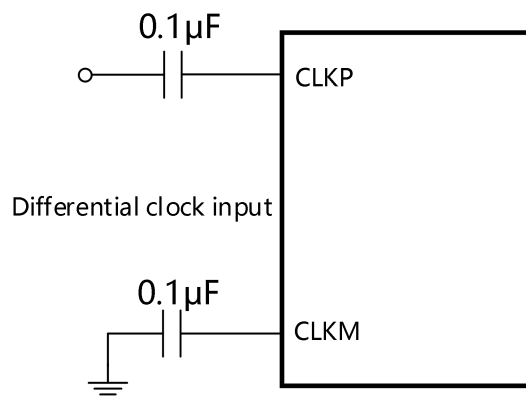
Figure 2.4 differential clock driving circuit

5. Digital Function

The default mode of devices is low latency mode and, in this mode, none digital function of devices switch ON. the 'low latency mode' registers are filled with '1'.The function which can initialize digital function include gain calibration, Offset calibration and test mode，refer to Figure 2.5.

Figure 2.5 differential clock driving circuit

Register Map

- **Register List**

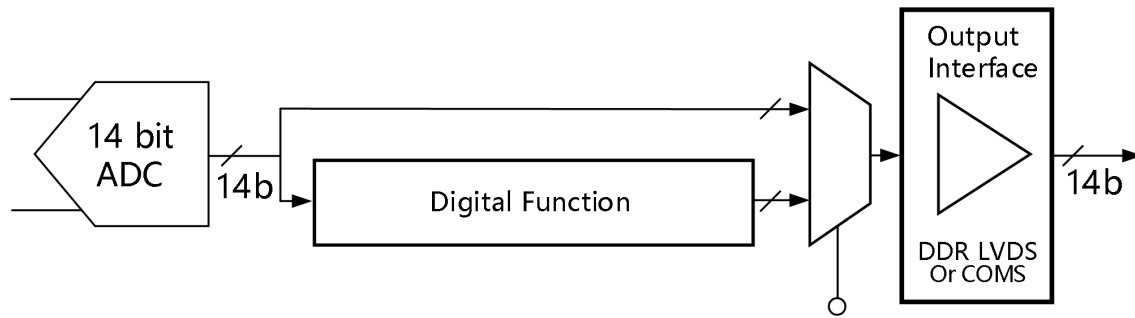| Register Address	Default value	Register data							
A[7:0] (Hex)	D[7:0](Hex)	D7	D6	D5	D4	D3	D2	D1	D0
00	00	0	0	0	0	0	0	Reset	Readout
01	00	LVDS Swing Programming: 000000 = Default LVDS swing; ±350mV with external 100Ω termination 011011 = Increase LVDS swing to ±410mV 110010 = Increase LVDS swing to ±465mV 010100 = Increase LVDS swing to ±570mV 111110 = Decrease LVDS swing to ±200mV 001111 = Decrease LVDS swing to ±125mV						0	0
03	00	0	0	0	0	0	0	High Perf Mode 1	
25	00	Gain Programmable： 0000 = 0dB gain (default) 0001 = 0.5dB gain 0010 = 1.0dB gain 0011 = 1.5dB gain 0100 = 2.0dB gain 0101 = 2.5dB gain 0110 = 3.0dB gain 0111 = 3.5dB gain 1000 = 4.0dB gain 1001 = 4.5dB gain 1010 = 5.0dB gain 1011 = 5.5dB gain				Gain Setting: 0 = Gain enabled; If the low-latency mode is disabled, the gain is set only by the	Test Mode 000 = Normal operation 001 = All outputs are 0 010 = All outputs are 1 011 = Output switching mode In CBM41AD49, D[13:0] is 01010101010101 and 10101010101010 100 = Output digital ramp In CBM41AD49, the output data increases by 1LSB in each clock cycle within the range of 0 to 16383		

								LVDS Output Clock Buffer Strength	LVDS Data Buffer Strength
		1100 = 6.0dB gain				GAIN bit. 1 = Gain disabled.		101 = Output custom mode (Set the custom mode using registers Ox3F and Ox40) 110 = Not used 111 = Not used	
26	00	0	0	0	0	0	0	LVDS Output Clock Buffer Strength 0 = 100Ω external node (default strength); 1 = 50Ω external node (double strength)	LVDS Data Buffer Strength 0 = 100Ω external node (default strength); 1 = 50Ω external node (double strength)
3D	00	Data format: 00 = The DFS pin controls the data format selection. 10 = Two's complement. 11 = Offset binary.	Offset Correction Setting 0 = Offset correction is disabled; 1 = Offset correction is enabled.	0	0	0	0	0	
3F	00	Traditional Mode High Bits D[13:6] In CBM41AD49, these bits configure the traditional output mode where data bits 13							

		to 0 are formatted as D[13:0] in traditional mode.				
40	00	Traditional mode D[5:0]			0	0
41	00	LVDS/CMOS Interface Selection: 00 = DFS pin controls LVDS or CMOS interface selection 10 = DFS pin controls LVDS or CMOS pin interface selection 01 = DDR LVDS interface 11 = Parallel CMOS interface Note: DFS = Data Format Select	CMOS Output Clock Strength Control: 00 = Maximum strength (recommended and used for specified timing) 01 = Medium strength 10 = Low strength 11 = Very low strength Note: Higher strength provides better signal integrity but may increase EMI.	Enable Output Clock Rising Edge: 0 = Disable output clock rising edge 1 = Enable output clock rising edge Note: This setting affects the clock signal edge used for data transmission.	Output Clock Rising Edge Control (Controls rising edge position): LVDS Interface: 00 = Default position (timing specified under this condition) 01 = Setup reduced by 500ps, Hold increased by 500ps 10 = Data transition aligned with rising edge 11 = Setup reduced by 200ps, Hold increased by 200ps Note: Adjustments optimize timing margins for specific applications.	Enable the falling edge of the output clock: 0 = Disable the falling edge of the output clock 1 = Enable the falling edge of the output clock
42	00	Enable the falling edge of the output clock: 0 = Disable the falling edge of the output clock 1 = Enable the falling edge of the output clock	0	0	Disable Low Latency Mode: 0 = Low latency mode is enabled, and gain,	Standby Mode: 0 = Normal operation. 1 = Only the ADC and the

Note: last row also has columns with 0 and 0 at far right.

					test mode, and offset correction are disabled; 1 = Low latency mode is turned off, and the digital algorithm function is enabled.	output buffer are powered off. The internal reference is activated, and the standby wake-up time is fast.		
43	00	0	Power-off: 0 = Normal operation; 1 = Complete power-off. The ADC, internal reference, and output buffer are all powered off, and the	0	Output Buffer Power Down: 0 = Output data and clock pins enabled; 1 = Output data and clock pins powered down Note:	0	0	LVDS Swing Control: 00 = LVDS swing control using the LVDS swing register is disabled; 01 = Not used; 10 = Not used; 11 = LVDS swing control using the LVDS swing register is enabled. Note: Only bit combinations 00 and 11 are functional.

			wake-up time is slow.		When powered down, outputs are in high impedance state.			
4A	00	0	0	0	0	0	0	0	High-performance Mode 2: 0= Default performance after reset; 1=Set the best performance for high-frequency input signals.
BF	00	Set Offset Base: When offset correction is enabled, the final converged value after offset correction becomes the code value in the ADC. By programming these bits, a base value can be added to the final converged value. CBM41AD49 Values and Bases: 011111 31LSB 011110 30LSB 011101 29LSB - - 000000 0LSB - - 111111 -1LSB 111110 -2LSB - - 100000 -32LSB					0	0

		Note: LSB = Least Significant Bit. Binary values from 011111 to 100000 represent a range from +31 to -32 LSB.				
CF	00	Freeze Offset Correction: 0= Offset correction is not frozen; 1= Offset correction is frozen. Note: When frozen, the current offset correction value is maintained.	0	Offset Correction Time Constant:Value Time Constant (Cycles) 0000 1M 0001 2M 0010 4M 0011 8M 0100 16M 0101 32M 0110 64M 0111 128M 1000 256M 1001 512M 1010 1G 1011 2G	0	0

SFDR/SNR Trade-off in Gain Configuration.The CBM41AD49 features a gain adjustment function to improve SFDR. Gain can be set from 0 to 6dB via the gain register shown above. The table below shows the relationship between gain settings and analog input ranges. SFDR improvement comes at the cost of SNR, which decreases by approximately 0.5 to 1dB per gain step. The rate of SNR decline slows for high-frequency inputs, making gain configuration particularly effective for high-frequency signals where SFDR improves significantly with minimal SNR loss. This feature enables SFDR/SNR trade-off optimization.

After reset, the gain configuration function is disabled in low-latency mode. To enable:

1.Disable low-latency mode (DIS LOW LATENCY = 1).

2.These settings enable gain and set the device to 0dB gain mode.

3.For other gain settings, configure the gain bits in the register.

Note: SNR degradation is approximately 0.5-1dB per dB of gain increase, with reduced impact at higher frequencies.

GAIN（dB）	TYPE	FULL-SCALE(V_{PP})
0	Default after reset	2
1	Programmable	1.78
2	Programmable	1.59
3	Programmable	1.42
4	Programmable	1.26
5	Programmable	1.12
6	Programmable	1.00

Matters Need Attention

1. installation：

1) The shipshape ground is required for the circuit board of application object.

2) The application object should used multiwiring board including independence ground layer.

3) The digital grounding and analog grounding of circuit board of application object should be separated as far as possible, digital line can not arrange beside of analog line or under the ADC.

4) AVDD, DRVDD and VCM should connect to ceramic bypass capacity of high quality and bypass capacity should approach pins, the line connecting pins to the bypass capacity is the shorter the better and the wider the better.

2. usage：

1) Differential input should approach as much as possible and parallel each other.

2) Input wires should be short as much as possible to minimize the input of parasitic capacitance and noise.

3) For better rejection of heat and obtain better performance, motherboard of chip should be soldering to the big ground terminal of PCB, in this way thermal performance of package would be take advantage to the maximum.

4) It is important that the ground of chip should be connected to the PCB through as many channels as possible and plentiful area.

3. protection：

1) Electrostatic Charge is easy to accumulate on human body and test equipment, discharge will be probably generated in the case of without notice. Although this product has special protection circuit for ESD, high energy electrostatic discharge may cause permanent damage to the device. It is recommended that the appropriate measure of ESD protective should be taken to avoid that the devices not to meet its published specifications or loss function.

2) Stresses beyond those listed under "maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Common Failure Treatment method

1. zero output signal: Checking whether the Power supply voltage，Input Signal or clock are correct loading.
2. overflow signal occurs: Checking whether reference circuit is normal operation and whether amplitude of input signal is OK.
3. the device is unstable: Checking the power for guaranteeing stability of supply voltage

Package Outline Dimensions

QFN-48

UNIT:mm

Package/Ordering Information

MODEL	ORDERING NUMBER	TEMPERATURE	PACKAGE DESCRIPTION	PAKEAGE OPTION	MAKING INFORMATION
CBM41AD49QF		-40℃-85℃	QFN-48	Tray，260	